



GE Energy

Functional Testing Specification

*Parts & Repair Operations
Louisville, KY*

LOU-GED-IC3600TSKB-A

Test Procedure for a IC3600TSKB1

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1. SCOPE

1.1 This is a functional testing procedure for an IC3600TSKB Card.

2. STANDARDS OF QUALITY

2.1 Refer to the current revision of the IPC-A-610 standard for workmanship standards.

3. APPLICABLE DOCUMENTS

3.1 The following document(s) shall form part of this specification to the extent specified herein. Unless otherwise indicated, the latest issue shall apply.

3.1.1 **QSI 2174**

4. ENGINEERING REQUIREMENTS

4.1 Equipment Cleaning

4.1.1 Equipment should be clean and free of debris prior to applying power unless performing an initial check. Refer to the local documented procedures for cleaning guidelines.

4.2 Equipment Inspection

4.2.1 Equipment should be visually inspected for any defects prior to applying power. This inspection should include the following as a minimum:

4.2.1.1 Wires - broken, cracked, or loosely connected

4.2.1.2 Terminal strips / connectors - broken or cracked

4.2.1.3 Components - visually damaged

4.2.1.4 Capacitors - bloated or leaking

4.2.1.5 Solder joints - damaged or cold

4.2.1.6 Circuit board - burned or de-laminated

4.2.1.7 Printed wire runs / Traces - burned or damaged

5. EQUIPMENT REQUIRED

5.1 The following equipment is required to perform the process requirements. Equipment may be substituted provided that all accuracy's and test ratios are equivalent or better.

Qty	Reference #	Description
1		DVM

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6. TESTING PROCESS

6.1 Setup

- 6.1.1 Apply a +67V to pin 24 and com. to pin 1.
- 6.1.2 Apply +5V through a 5.6k ohm to pin 45 and com. to pin 1.
- 6.1.3 Apply +5V through a 5.6k ohm to pin 46 and com. to pin 1.
- 6.1.4 Apply +5V through a 5.6k ohm to pin 48 and com. to pin 1.

6.2 Testing Procedure

- 6.2.1 Apply power.
- 6.2.2 Pin 20 to pin 6 should read 10K ohms.
- 6.2.3 Pin 20 to pin 8 should read < 2 ohms.
- 6.2.4 Apply +5V to pin 25 com. to pin 1.
- 6.2.5 Pin 20 to pin 8 should now read open.
- 6.2.6 Pins 45, 46 and 48 should now read +5V.
- 6.2.7 Remove +5V from pin 25.
- 6.2.8 Pins 45,46 and 48 should now read zero volts after a 1.5 second delay.
- 6.2.9 Reapply +5V to pin 25 and pins 45, 46 and 48 should again read +5V.
- 6.2.10 Remove +67V from pin 24.
- 6.2.11 Pin 48 should read +5V.
- 6.2.12 Reapply +67v to pin 24 and pin 48 should go to zero and then back to +5V.
- 6.2.13

6.3 Post Testing Burn-in Required ___ Yes x No



Note: All MARK I, II, & III Turbine related cards require a post testing burn-in of 100 hours.

- 6.3.1 Apply BUS or Operational power to the card for a period of 100 hours.
- 6.3.2 Re-test card while warm using the above procedure.

6.4 *****TEST COMPLETE*****

7. NOTES

- 7.1 None at this time.

8. ATTACHMENTS

- 8.1 None at this time.